

April 2000

QFET™

FQA15N70

700V N-Channel MOSFET

General Description

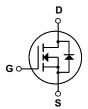
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply.

Features

- 15A, 700V, $\rm R_{DS(on)}$ = 0.56 Ω @ $\rm V_{GS}$ = 10 V
- Low gate charge (typical 70 nC)
- Low Crss (typical 27 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings $T_C = 25$ °C unless otherwise noted

Symbol	Parameter		FQA15N70	Units	
V _{DSS}	Drain-Source Voltage		700	V	
I _D	Drain Current - Continuous (T _C = 25°C	;)	15	A	
	- Continuous (T _C = 100°	C)	9.5	А	
I _{DM}	Drain Curent - Pulsed	(Note 1)	60	А	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	950	mJ	
I _{AR}	Avalanche Current	(Note 1)	15	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	30	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		300	W	
	- Derate above 25°C		2.38	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.42	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	700			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°	C	0.68		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 700 V, V _{GS} = 0 V			10	μΑ
		V _{DS} = 560 V, T _C = 125°C			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Chr	aracteristics	1	"		I.	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 7.5 A		0.43	0.56	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 7.5 A (Note	4)	15		S
C _{rss}	Reverse Transfer Capacitance	t = 1.0 MHz		27	390	pF pF
C _{oss}	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		300 27	390 35	pF nF
0 11 1						
	ing Characteristics			70	450	
t _{d(on)}	Turn-On Delay Time	V _{DD} = 350 V, I _D = 15 A,		70	150	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		180	370	ns
ld(off)	Turn-Off Delay Time	(Note 4	. 5)	160 120	330	ns
	Turn Off Fall Time				250	ns
t _f	Turn-Off Fall Time	,				20
t _f Q _g	Total Gate Charge	V _{DS} = 560 V, I _D = 15 A,		70	90	nC
t _f Q _g Q _{gs}	Total Gate Charge Gate-Source Charge	V _{DS} = 560 V, I _D = 15 A, V _{GS} = 10 V		70 17	90	nC
t _f Q _g Q _{gs}	Total Gate Charge	V _{DS} = 560 V, I _D = 15 A,		70	90	
t _f Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge	V_{DS} = 560 V, I_{D} = 15 A, V_{GS} = 10 V (Note 4		70 17	90	nC
t _f Q _g Q _{gs} Q _{gd} Drain-S	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V_{DS} = 560 V, I_{D} = 15 A, V_{GS} = 10 V (Note 4)		70 17	90	nC
t _f Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics ar	V _{DS} = 560 V, I _D = 15 A, V _{GS} = 10 V (Note 4) And Maximum Ratings and Forward Current	, 5)	70 17 33	90	nC nC
t _f Q _g Q _{gs} Q _{gd} Drain-S I _S I _{SM}	Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics and Maximum Continuous Drain-Source Diode	V _{DS} = 560 V, I _D = 15 A, V _{GS} = 10 V (Note 4) And Maximum Ratings and Forward Current	, 5)	70 17 33	90	nC nC
I _S	Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics and Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	V _{DS} = 560 V, I _D = 15 A, V _{GS} = 10 V (Note 4) And Maximum Ratings ode Forward Current Forward Current	. 5)	70 17 33	90 15 60	nC nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 7.8mH, I_{AS} = 15A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25°C 3. $I_{SD} \leq$ 15A, didt \leq 200A/µs, $V_{DD} \leq$ BV $_{DSS}$, Starting T_{J} = 25°C 4. Pulse Test : Pulse width \leq 300µs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

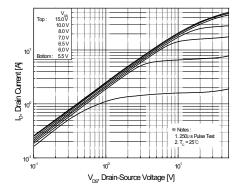


Figure 1. On-Region Characteristics

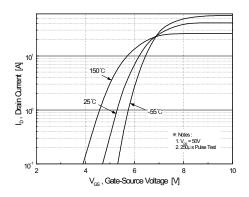


Figure 2. Transfer Characteristics

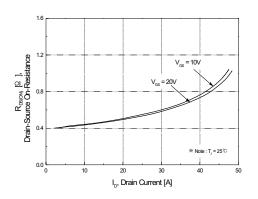


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

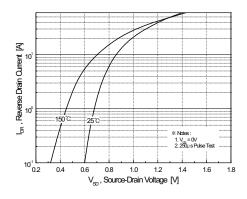


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

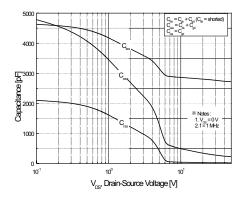


Figure 5. Capacitance Characteristics

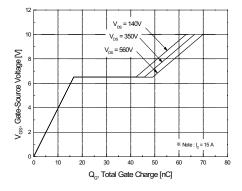
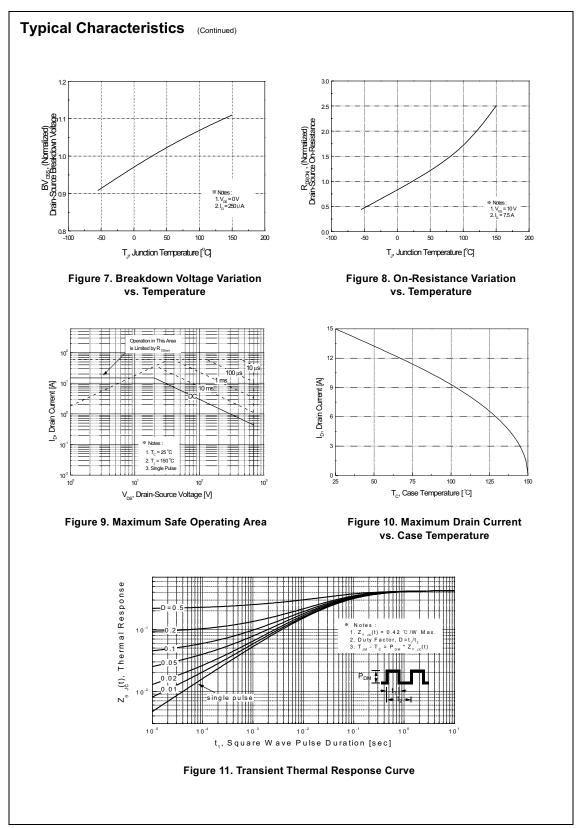
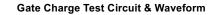


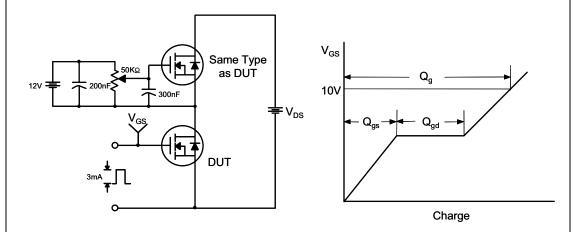
Figure 6. Gate Charge Characteristics

Rev. A, April 2000

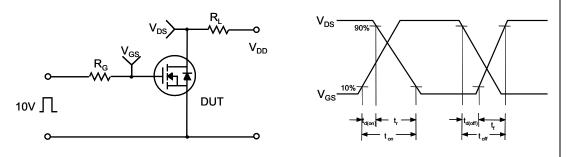


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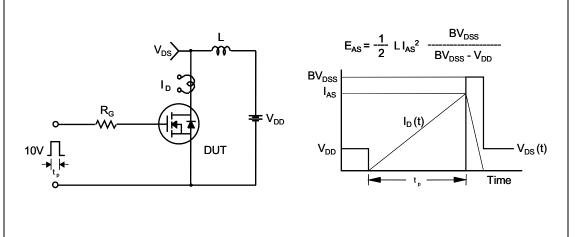


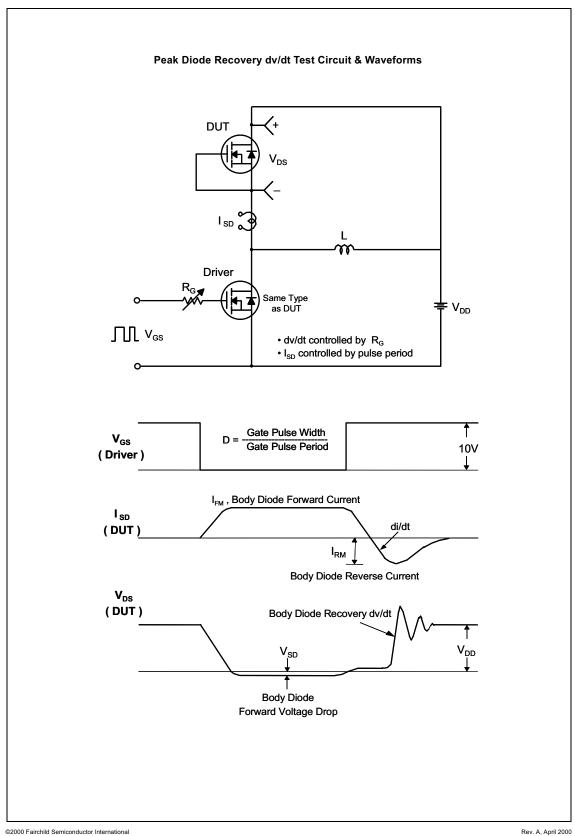


Resistive Switching Test Circuit & Waveforms

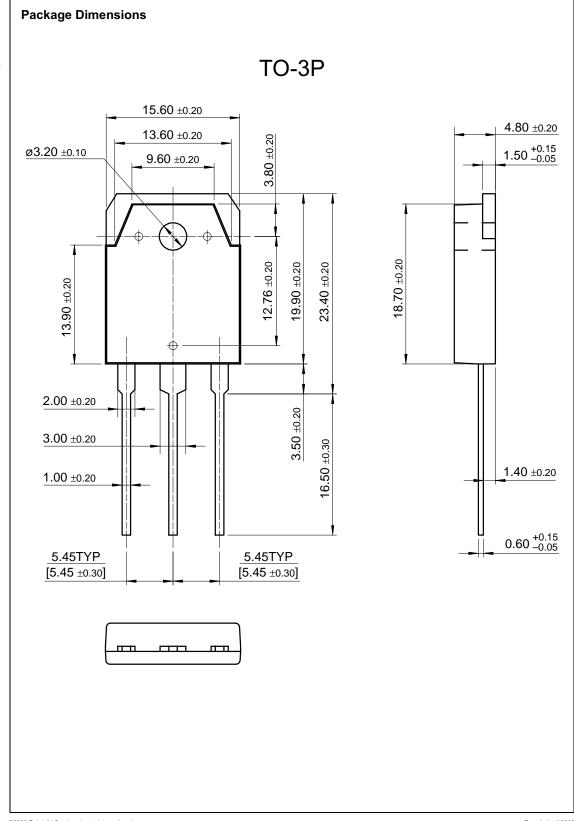


Unclamped Inductive Switching Test Circuit & Waveforms









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 $\begin{array}{lll} \mathsf{FAST}^{\circledR} & \mathsf{Quiet} \ \mathsf{Series}^{\intercal \mathsf{M}} \\ \mathsf{FASTr}^{\intercal \mathsf{M}} & \mathsf{SuperSOT}^{\intercal \mathsf{M}}\text{-}3 \\ \mathsf{GTO}^{\intercal \mathsf{M}} & \mathsf{SuperSOT}^{\intercal \mathsf{M}}\text{-}6 \end{array}$

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